

TITLE**IMPROVED PROBE FOR INTEGRATED CIRCUIT TEST SOCKET****Abstract**

An improved probe for use in test sockets of automatic test equipment for packaged integrated circuits that allows longer intervals between replacement of equipment components is described. The present invention has a plurality of contact points available to contact a trace of the test equipment allowing circuitry with worn traces to remain serviceable for a longer period of use. The present invention also has a toothed contact arm to allow for easier cleaning of solder accumulation and a secondary support to reduce impact on spring elements of the test socket.

FIG. 2 accompanies the abstract.